

CY Chingyao Fu

Senior Director of Product Management,
Smart Vehicle Division (SVD),
Industrial Automotive Business Group (IABG),
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PROFESSIONAL PROFILE

Entrepreneurship and execution oriented.

Well-know the manufacturing, engineering, and market challenges.

3 years' entrepreneurial experience for handheld NIR detecting equipment.

23 years of experience in the design, manufacturing and marketing of IC and electronic products.

EDUCATION

M.S. EECS, National Taipei University of Technology, Taipei, TAIWAN, 2022-Now

M.S. EMBA, The University of Texas at Arlington, Texas, USA, 2022-Now

M.S. MEE, Chung Hua University, Hsinchu, TAIWAN, 1994-1996

A.D. EE, Ming Hsin Junior College, Hsinchu, TAIWAN, 1986-1991

SERVICE

Senior Director of Product Management, Wistron, Oct 2019 - Now

UAV(drone) Product Line Management

Commercial EV Product Line Management

Acoustic Product Line Management (Before Dec 2021)

Senior Manager of Product and Business Development, Foxconn, Apr 2017 - Sep 2019

Belkin Linksys Networking Product China SMB Sales Management

Implement Smart Home Ecosystem To China Market

Build Up Smart Camera, Smart Mesh Gateway, Smart Speaker Product Lines.

GM And Founder, Magispec Technology, Apr 2015 - Apr 2017

Lead And Managed An Entrepreneurial Team.

Developed A Low Cost NIR Milk Analyzer For China Market

Developed A Portable Fast Drug Detector By NIR spectrum Technology For Police Department .

Senior Manager of Product Management, Foxconn, Apr 2010 - Apr 2015

Apple WiFi Module Business Management.

China(Xiaomi, Baidu, Alibaba, Lenovo) Market Business Management.

OTT and WiFi Router Related Product Lines Management.

Engineering, RD, Sales Manager of PKG BU, Foxconn, Feb 1999 - Apr 2010

RF Modules, WiFi Modules, Optical Modules Business Management.

Build Up ISO9000 And QS9000 Procedures.

Build Up Engineering And RD Teams.

Product And Testing Section Manager, MOST Semiconductor, Jun 1996 - Feb 1999

Process Engineer For Photo-coupler And MMIC.

RF Testing Engineer For MMIC.

Trained in NEC, Japan.

CERTIFICATES AND AWARDS

2010 Year Excellent Manager of Hon-Hai Precision Co. Ltd.

2003 6 Sigma Green-belt

1997 Taiwan Radioactive Materials or Ionizing Radiation Equipment Operating License

PUBLICATIONS

TW201123869A	Camera module and method of manufacturing same
TW201103114A	Flat chip package structure and method thereof
TW201042749A	Integrated package assembly
TW201039424A	Method and assembly of welding flip chip on a substrate
TW201039413A	Chip package assembly and substrate processing method thereof
TW201036115A	Assembly and method of chip package
TW201032687A	Method for levelling surface of LGA substrate
TW200947632A	Semiconductor package structure and method same
CN107280679A	Intelligent infant monitoring care system and operation method thereof
CN107280561A	Infant intelligent toilet seat and intelligent toilet seat system
CN102045494A	Camera module and making method thereof
CN101937886A	Thin chip package structure and method

CN101894829A	Stacked encapsulating structure
CN101872727A	Chip welding method and structure
CN101866886A	Chip packaging structure and substrate processing method thereof
CN101834162A	Chip packaging structure and method
CN101826468A	Method for manufacturing substrate
CN101937886B	Thin chip package structure and method
CN101894829B	Stacked encapsulating structure

SKILLS

Hardware	IC Package, SMT, System Assembly, Testing And Failure Analysis Equipment
Software	Python, C, Java, LaTeX
Mechanical	ProE, AutoCad
Design/Simulation	PSpice, Protel, Allego, Matlab, Illustrator, Keyshot, ArduPilot